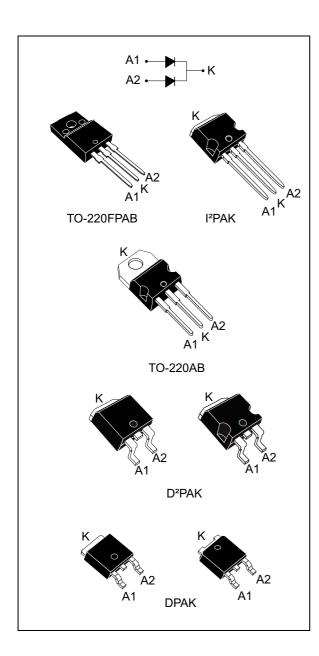




High efficiency ultrafast diode

Datasheet - production data



Features

- Suited for SMPS
- Low losses
- Low forward and reverse recovery times
- Insulated package: TO-220FPAB
 - Insulating voltage: 2000 V_{RMS} sine
- High junction temperature
- Low leakage current
- ECOPACK[®]2 compliant component for DPAK and D²PAK on demand

Description

Dual center tap rectifier suited for switch mode power supplies and high frequency DC to DC converters.

Packaged in DPAK, D²PAK, TO-220AB, I²PAK and TO-220FPAB, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

Table 1. Device summary

Symbol	Value
I _{F(AV)}	Up to 2 x 8 A
V _{RRM}	200 V
T _j (max)	175 °C
V _F (typ)	0.78 V
t _{rr} (typ)	20 ns

Characteristics STTH1002C

1 Characteristics

Table 2. Absolute ratings (limiting values per diode at 25 °C, unless otherwise specified)

Symbol		Parameter				
V_{RRM}	Repetitive peak reverse voltage				200	V
	Forward rms current	I ² PAK, D ² PAK,T	O-220AB, TO	-220FPAB	20	Α
I _{F(RMS)}	Polward mis current		DPAK		10	A
			T _C = 155 °C	Per diode	5	
		I ² PAK, DPAK,	C	Per device	10	A
	Average forward current		T _C = 135 °C	Per diode	8	
			T _C = 125 °C	Per device	16	
I _{F(AV)}	δ = 0.5, square wave		T _C = 140 °C	Per diode	5	A
		TO-220FPAB	T _C = 120 °C	Per device	10	
		10-220FPAB	T _C = 110 °C	Per diode	8	
			T _C = 75 °C	Per device	16	
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$					Α
T _{stg}	Storage temperature range				-65 to +175	°C
T _j	Maximum operating junction temperature				175	°C

Table 3. Thermal parameter

Symbol		Parameter				
		I ² PAK, DPAK, D ² PAK,TO-220AB		4.0		
ь	R _{th(j-c)} Junction to case	I FAR, DFAR, D FAR, 10-220AB	Per device	2.5		
Kth(j-c)		TO-220FPAB	Per diode	6.5	°C/W	
		TO-220FFAB	Per device	5.0	C/VV	
D	Coupling	I ² PAK, DPAK, D ² PAK,TO-220AB		1.0		
R _{th(c)} Coupling		TO-220FPAB	3.5			

When the diodes 1 and 2 are used simultaneously:

 ΔT_j (diode1) = P(diode1) x $R_{th(j-c)}$ (per diode) + P(diode2) x $R_{th(c)}$

STTH1002C Characteristics

Table 4. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	$T_j = 25 ^{\circ}\text{C}$		-		5	пΛ
'R`	inteverse leakage current	T _j = 125 °C	$V_R = V_{RRM}$	-	3	40	μA
		T = 25 °C	I _F = 5 A	-		1.10	
V _E (2)	Forward voltage drop	T _j = 25 °C	I _F = 10 A	-		1.25	V
VF`	Polward voltage drop	T _ 150 °C	I _F = 5 A	-	0.78	0.89	V
		T _j = 150 °C	I _F = 10 A	-		1.05	

- 1. Pulse test: $t_p = 5$ ms, $\delta < 2\%$
- 2. Pulse test: t_p = 380 μ s, δ < 2%

To evaluate the conduction losses, use the following equation:

$$P = 0.73 \times I_{F(AV)} + 0.032 \times I_{F}^{2}_{(RMS)}$$

Table 5. Dynamic electrical characteristics (per diode)

Symbol	Parameter	1	Test conditions	Min.	Тур.	Max.	Unit
t _{rr}	Reverse recovery time	T _j = 25 °C	$I_F = 1 A$ $V_R = 30 V$ $dI_F/dt = 100 A/\mu s$	-	20	25	ns
I _{RM}	Reverse recovery current	T _j = 125 °C	$I_F = 5 \text{ A}$ $V_R = 160 \text{ V}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$	-	5.9	7.6	А
t _{fr}	Forward recovery time	T _j = 25 °C	$I_F = 5 A$ $V_{FR} = 1.1 \times V_{Fmax}$ $dI_F/dt = 100 A/\mu s$	-		110	ns
V _{FP}	Forward recovery voltage		I _F = 5 A dI _F /dt = 100 A/μs	-	2.4		V

Characteristics STTH1002C

Figure 1. Peak current versus duty cycle (per diode)

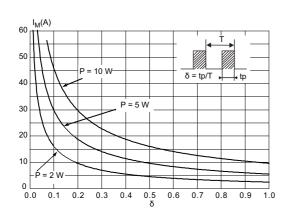


Figure 2. Forward voltage drop versus forward current (typical values, per diode)

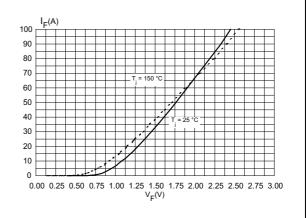


Figure 3. Forward voltage drop versus forward current (maximum values, per diode)

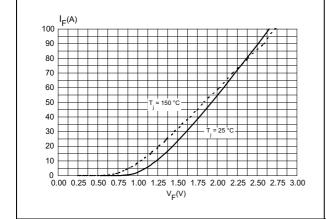


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

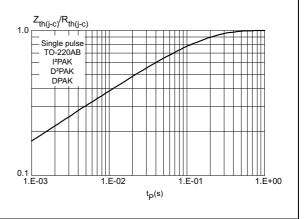


Figure 5. Relative variation of thermal impedance junction to case versus pulse duration

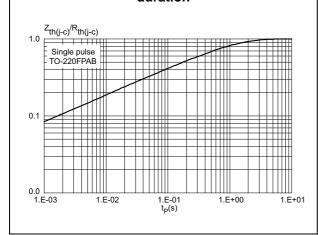
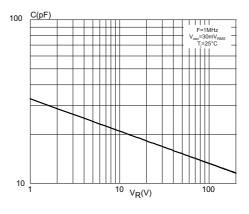


Figure 6. Junction capacitance versus reverse voltage applied (typical values, per diode)



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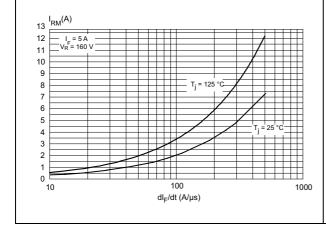
STTH1002C Characteristics

Figure 7. Reverse recovery charges versus dl_F/dt (typical values, per diode) $Q_{rr}(nC)$ 240 220 I_F = 5 A V_R= 160 V 200 180 160 140 120 100 80 60 40 20 0 10 1000

Figure 8. Reverse recovery time versus dl_F/dt (typical values, per diode) t_{rr}(ns) 80 70 60 50 40 30 20 10 0 <u></u> 100 dl_F /dt (A/μs) 1000

Figure 9. Peak reverse recovery current versus | Figure 10. Dynamic parameters versus junction dl_F/dt (typical values, per diode)

dl_F/dt (A/μs)



temperature (reference: T_i = 125 °C)

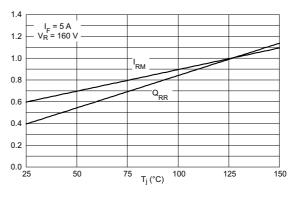


Figure 11. Thermal resistance junction to ambient versus copper surface under tab

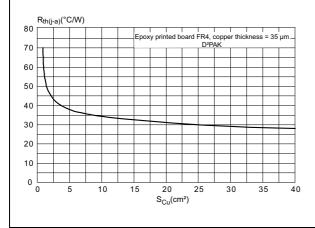
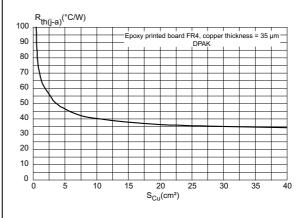


Figure 12. Thermal resistance junction to ambient versus copper surface under tab



2 **Package information**

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value:0.55 N·m for TO-220AB and TO-220FPAB
- Maximum torque value: 0.7 N·m for TO-220AB and TO-220FPAB

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

2.1 **TO-220AB** package information

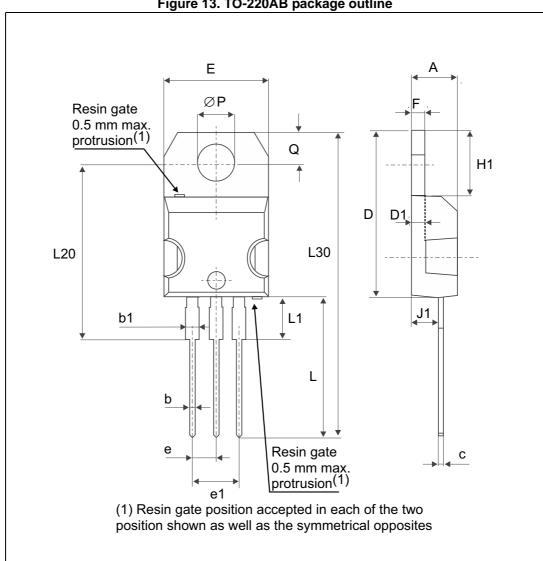


Figure 13. TO-220AB package outline

STTH1002C Package information

Table 6. TO-220AB package mechanical data

		Dimer	nsions		
Ref.	Millim	neters	Incl	hes	
	Min.	Max.	Min.	Max.	
А	4.40	4.60	0.170	0.181	
b	0.61	0.88	0.024	0.035	
b1	1.14	1.70	0.045	0.067	
С	0.48	0.70	0.019	0.027	
D	15.25	15.75	0.600	0.620	
D1	1.27	typ.	0.050	typ.	
E	10.00	10.40	0.393	0.41	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.194	0.202	
F	1.23	1.32	0.048	0.052	
H1	6.20	6.60	0.244	0.259	
J1	2.40	2.72	0.094	0.107	
L	13.00	14.00	0.511	0.551	
L1	3.50	3.93	0.137	0.154	
L20	16.40 typ.		0.645 typ.		
L30	28.90 typ.		1.137 typ.		
ØP	3.75	3.85	0.147	0.151	
Q	2.65	2.95	0.104	0.116	

2.2 TO-220FPAB package information

Ĥ Dia L6 L2 L7 L3 L5 D L4 **F2** Ε G

Figure 14. TO-220FPAB package outline

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Table 7. TO-220FPAB package mechanical data

		Dimer	nsions		
Ref.	Millin	neters	Inc	hes	
	Min.	Max.	Min.	Max.	
А	4.40	4.60	0.173	0.181	
В	2.50	2.70	0.098	0.106	
D	2.50	2.75	0.098	0.108	
E	0.45	0.70	0.018	0.027	
F	0.75	1.00	0.030	0.039	
F1	1.15	1.70	0.045	0.067	
F2	1.15	1.70	0.045	0.067	
G	4.95	5.20	0.195	0.205	
G1	2.40	2.70	0.094	0.106	
Н	10.00	10.40	0.393	0.409	
L2	16.00	Тур.	0.630 Typ.		
L3	28.60	30.60	1.126	1.205	
L4	9.80	10.60	0.386	0.417	
L5	2.90	3.60	0.114	0.142	
L6	15.90	16.40	0.626	0.646	
L7	9.00	9.30	0.354	0.366	
Dia.	3.00	3.20	0.118	0.126	

2.3 D²PAK package information

<u>c2</u> L1 D Н L2 b b2 E1 D1 <u>A1</u> D2 L 0.25 Gauge plane

Figure 15. D²PAK package outline

Note:

This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

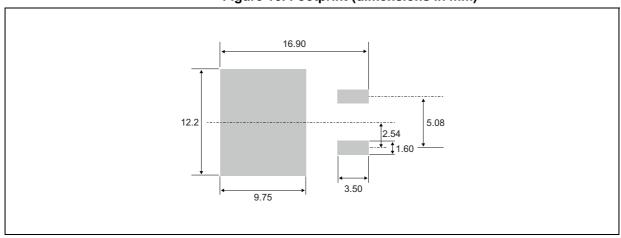
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STTH1002C Package information

Table 8. D²PAK package mechanical data

			Di	mensions		
Ref.		Millimeters			Inches	
	Min.	Тур.	Max.	Min.	Тур.	Max.
А	4.36		4.60	0.171		0.181
A1	0		0.25			0.010
b	0.70		0.93	0.027		0.037
b2	1.14		1.70	0.045		0.067
С	0.38		0.69	0.014		0.027
c2	1.19		1.36	0.046		0.053
D	8.60		9.35	0.338		0.368
D1	6.90		8.00	0.271		0.315
D2	1.10		1.50	0.043		0.060
Е	10.00		10.55	0.393		0.415
E1	8.10		8.90	0.318		0.350
E2	6.85		7.25	0.269		0.285
е		2.54			0.100	
e1	4.88		5.28	0.192		0.208
Н	15.00		15.85	0.590		0.624
J1	2.49		2.90	0.098		0.114
L	1.90		2.79	0.074		0.110
L1	1.27		1.65	0.050		0.065
L2	1.30		1.78	0.051		0.070
R		0.40			0.016	•
V2	0°		8°	0°		8°

Figure 16. Footprint (dimensions in mm)



2.4 DPAK package information

Thermal pad

E1

A2

A2

A3

Gauge

0.25 plane

Figure 17. DPAK package outline

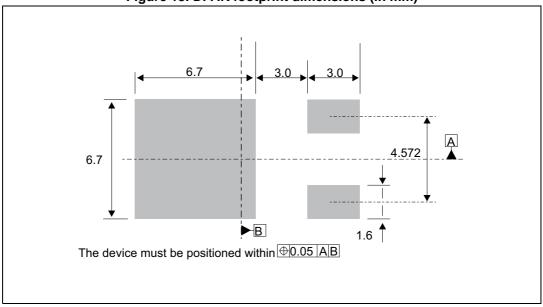
Note: This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

57

Table 9. DPAK package mechanical data

			ı	Dimensions			
Ref.		Millimeters			Inches	S	
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	2.18		2.40	0.085		0.094	
A1	0.90		1.10	0.035		0.043	
A2	0.03		0.23	0.001		0.009	
b	0.64		0.90	0.025		0.035	
b4	4.95		5.46	0.194		0.214	
С	0.46		0.61	0.018		0.024	
c2	0.46		0.60	0.018		0.023	
D	5.97		6.22	0.235		0.244	
D1	4.95		5.60	0.194		0.220	
E	6.35		6.73	0.250		0.264	
E1	4.32		5.50	0.170		0.216	
е		2.28			0.090		
e1	4.40		4.70	0.173		0.185	
Н	9.35		10.40	0.368		0.409	
L	1.00		1.78	0.039		0.070	
L2			1.27			0.050	
L4	0.60		1.02	0.023		0.040	
V2	-8°		+8°	-8°		8°	

Figure 18. DPAK footprint dimensions (in mm)



2.5 I²PAK package information

Figure 19. I²PAK package outline

е

e1

Table 10. I²PAK package mechanical data

	Dimensions					
Ref.	Millin	neters	Inc	hes		
	Min.	Max.	Min.	Max.		
А	4.40	4.60	0.173	0.181		
A1	2.40	2.72	0.094	0.107		
b	0.61	0.88	0.024	0.035		
b1	1.14	1.70	0.044	0.067		
С	0.49	0.70	0.019	0.028		
c2	1.23	1.32	0.048	0.052		
D	8.95	9.35	0.352	0.368		
е	2.40	2.70	0.094	0.106		
e1	4.95	5.15	0.195	0.203		
E	10.00	10.40	0.394	0.409		
L	13.00	14.00	0.512	0.551		
L1	3.50	3.93	0.138	0.155		
L2	1.27	1.40	0.050	0.055		

Ordering information STTH1002C

3 Ordering information

Table 11. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH1002CB	STTH1 002CB	DPAK	0.32 g	75	Tube
STTH1002CB-TR	STTH1 002CB	DPAK	0.32 g	2500	Tape and reel
STTH1002CT	STTH1002CT	TO-220AB	1.9 g	50	Tube
STTH1002CG-TR	STTH1002CG	D ² PAK	1.38 g	1000	Tape and reel
STTH1002CR	STTH1002CR	I ² PAK	1.5 g	50	Tube
STTH1002CFP	STTH1002CFP	TO-220FPAB	1.9 g	50	Tube

4 Revision history

Table 12. Document revision history

Date	Revision	Changes
Mar-2004	4	Last issue.
22-Mar-2013	5	Updated Table 7.
05-Jan-2015	6	Updated DPAK and D²PAK package information.
24-Apr-2015	7	Updated Figure 15.
20-Sep-2016	8	Updated DPAK package information and reformatted to current standard.

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